

BESTEMP

提升品质观念 · 创造客户价值



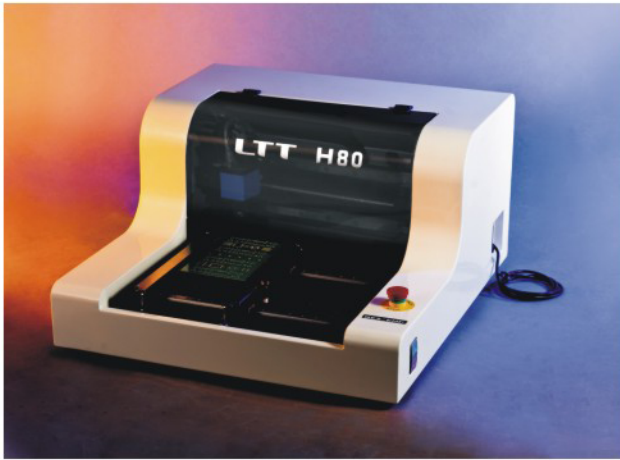
BESTEMP ELECTRONIC CO.,LTD.

LTT H80

3D 锡膏厚度测试仪 3D SOLDER PASTE INSPECTOR

☎ 400-000-5355

LTT-H80系列



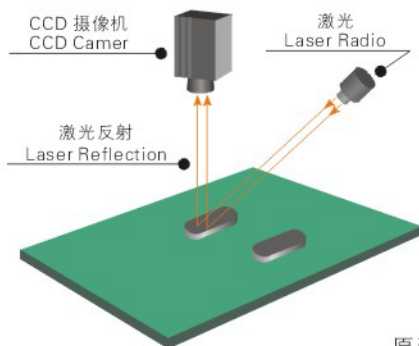
特点 / Features

- ❖ 大测量区330mm × 300mm (530mm X 460mm)，充分满足基板要求；
- ❖ 自动夹板功能，快速夹板定位，无须手动操作，可视化操作更简便，真正可编程测试；
- ❖ 通过PCB MARK自动寻找检查位置并校正偏移；
- ❖ 采用3轴自动移动、对焦，自动补偿修正基板翘曲变形，获取准确锡膏数据；
- ❖ 高速日本COOL MUSCLE 集成伺服系统，速度快，精度高；
- ❖ 同时可替代SMT坐标机使用，自动生成CP、CPK、X-BAR、R-CHART SIGMA柱形图、趋势图、管制图等、强大SPC数据统计分析；
- ❖ 扫描影像可进行截面切片测量与分析，影像同样可用于2D；
- ❖ 精密可靠的硬件系统，提供可信测量精度，增加使用寿命；
- ❖ 超越锡膏厚度测试的多功能测试；
- ❖ 测量结果数据列表自动保存，生成SPC报表方便查看；
- ❖ 330mmx300mm (530mmx460mm) Large measuring area to meet using request;
- ❖ Programmed test system and operation with quick and view ;
- ❖ Auto-search and inspect also rectify offset ;
- ❖ Autocom pensation and correct warp as well as distotion to get accurate data on solder paste;
- ❖ Integrated high-speed servo system of JaPan COOL MUSCLE with high speed and high precision;
- ❖ Powerful SPC analyse software for data statistic
- ❖ Warning and building CP、CPK、X-BAR、R-CHART、SIGMA histogram
- ❖ R&C&S&P distributing chart、straight chart、trend chart、control chart automatically;
- ❖ Inspection for section slip and analyse after scanning image ,as well as 2D;
- ❖ Exact and reliable hard system provide creditable data and long life;
- ❖ Muti-fuction test for over solder paste;
- ❖ Auto-save the test data and build SPC report so that review in future;

其它用途 /Others

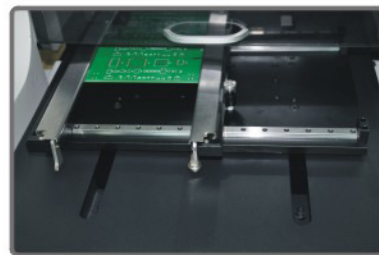
- ❖ IC封装、空PCB变形测量；
- ❖ 钢网的通孔尺寸和形状测量；
- ❖ PCB焊盘、丝印图案的厚度和形状测量；
- ❖ 提供刮刀压力预测功能、印刷制程优化功能；
- ❖ 芯片邦定、零件共平面度、BGA/CSP尺寸和形装测量；
- ❖ Encapsulation IC and measure for blank distion PCB;
- ❖ Measure steel mesh for through hole and shape;
- ❖ Measure thickness for solder tray and silk-screen patten;
- ❖ Provide forecast for pressure、optimize printing processing;
- ❖ Encapsulation chip、same planeness for accessoriys、
- ❖ Measure dimension and shape for BGA / CSP;

工作原理图 / WORK PRINCIPLE



Principle Show:
(Reflection laser to surface of object by laser head. then reflect to lensby surface of different heigh, transform into data by image processingo.)

原理说明：
(激光头发射激光经过被测物体表面，物体表面不同高度被反射到镜头，经过图像处理转化为数据。)

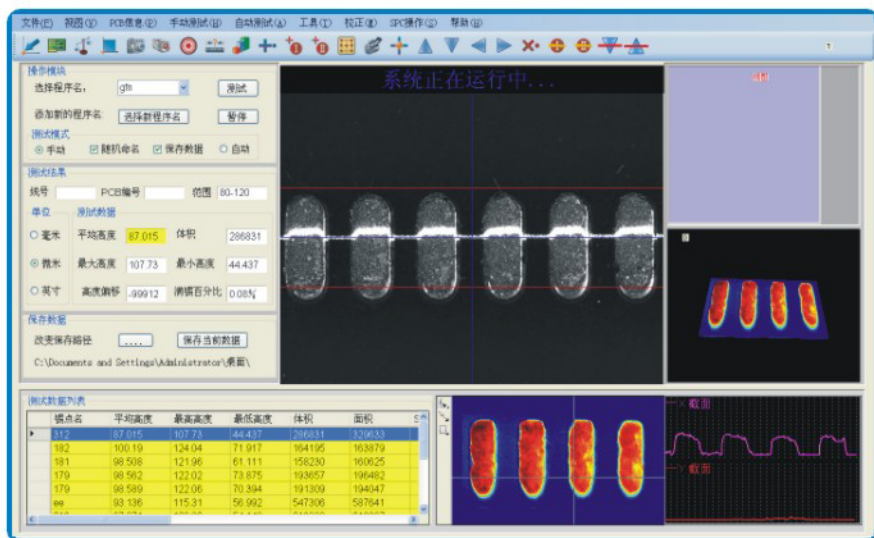


自动夹板功能
方便操作



采用激光焊接

软件分析 / Software Analyse



软件界面 / SOFT SURFACE

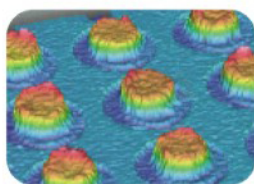


CPK 测试报告 CPK Test Report



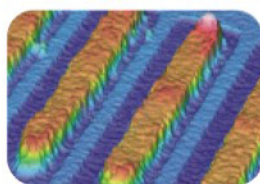
R.X_Bar Chart

测试效果 / Test Effection



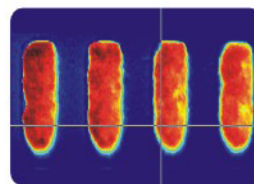
印刷机

- ❖ 工艺参数
- ❖ 连续、不规则的不良
- ❖ SMT工艺不良的主要原因

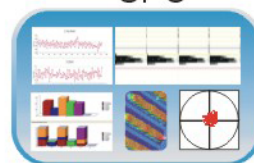


3D测厚仪

- ❖ 实时测量锡膏的高度、体积形状
- ❖ 消除SMT工程中的不良
- ❖ 提供工艺管理统计数据, 进行有效的优化



SPC



技术参数 / Parameters

最高测量精度	Tiptop measure precision(Z)	Height (Z) :0.5 μm	
重复精度	Repeat precision	Height :below 1.2 μm , Volume :below 1%	
放大倍率	Zoom multiple	50X	
光学检测系统	Optics inspection system	德国工业 CCD相机	
激光发生系统	Laser system	红光激光模组	Laser module with glowing
自动平台系统	Auto-system	全自动	Full automaticity
测量原理	Measure principle	非接触式激光束	Non-touch laser bean
X/Y可移动扫描范围	Scan area (X/Y)	330mm(X) × 300mm(Y) / 530mm(X) × 460mm(Y)	
最大可测量高度	Max measure height	5mm	
测量速度	Measure speed	最大150 Profiles / sec	Max 150 Profiles / sec
SPC 软件	SPC soft	Cp、Cpk、Sigma、Histogram Chat、X bar R&S、Trend、Scatter、Pdata report to Excel & Text	
计算机系统	PC system	惠普双核P4 20寸LCD Windows XP	
软件语言版本	Language	简体中文、繁体中文、英文	Simplified Chinese ,Traditional Chinese, English
电源	Power	单相 AC 220V, 60/50Hz	Single-phase AC 220V, 60/50Hz
重量	Weight	75kg	
设备外型尺寸	Product shape size	668(W) × 775(D) × 374(H) mm	
包装后尺寸	Packing size	790(W) × 880(D) × 630(H) mm	

配置清单 /Recorder Bills

	名称	Item	数量/Qty
1	主机	Host	1
2	说明书	User Manual	1
3	软件	Software CD	1
4	校正块	Standard Block	1
5	校证证书	Quality Certification	1
6	工控电脑	Industrial compuster	1
7	加密狗	Dongle	1

BESTEMP

服务承诺：

自购买产品12个月内，为您提供免费保修及软件升级、年度维护服务。
免费提供产品试用及校正服务。

Service promise:

Provide free repairing and software update since buying 12 months,as well as free maintenance yearly.

Provide free production attempt use and verifying service.

根据仪器型号规格不同，参数会发生变化，由于持续开发产品，因此参数规格若有变化恕不另行通知，请以实物为准。

The parameter will be different base on different model and standard, Will do not inform if parameter is being change due to development continuously. Please refer to actual product.

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